

ADHESIVES
A COMPREHENSIVE RANGE OF ADHESIVES FOR ELECTRONIC, AUTOMOTIVE AND GENERAL MANUFACTURING INDUSTRIES.

CONSUMABLES
ASSEMBLY MATERIALS AND MACHINE CONSUMABLES USED IN SEMICONDUCTOR, PHOTONIC AND HYBRID ASSEMBLY ETC.

EQUIPMENT
ASSEMBLY, TEST AND INSPECTION EQUIPMENT FOR THE MICROELECTRONIC, ELECTRONIC, PHOTONIC AND SEMICONDUCTOR INDUSTRIES.



Inseto

ADVANCED TECHNOLOGY FOR RESEARCH & INDUSTRY

CONNECT NEWSLETTER

Welcome to the twenty second issue of our Company Newsletter, "Inseto Connect", dedicated to providing information on new products, supplier & company news and technical announcements.

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Inseto Signs Deal to Distribute Tresky AG in the Nordic Region

Manual die bond and sort equipment specialist Tresky AG has signed an exclusive agreement with Inseto to extend sales and support of their products beyond the existing UK & Ireland area, to also now include the Nordic region comprising Denmark, Norway, Finland & Sweden.



Inseto to Sponsor IMAPS-UK 50th Annual Conference

Inseto is pleased to announce our continued support of IMAPS-UK, the Microelectronics Assembly & Packaging Society, with sponsorship of its forthcoming annual conference "MicroTech 2018".



The special event celebrates 50 Years since the foundation of ISHM (The International Society for Hybrid Microelectronics), the forerunner to today's IMAPS and comprises a Gala Awards & Networking Dinner on the evening of the 9th April and the main Conference on the 10th April, at the prestigious Royal Holloway Windsor Conference Centre in Egham Surrey.

The Gala Dinner will feature Company and Individual of the Year Awards, plus a keynote providing an insight into the future Technologies and Trends and a special presentation looking at the development of IMAPS-UK and the various microelectronics packaging technologies we see today.

Continuing the event's theme "MOORE THAN PACKAGING: 50 Years Gone; 50 Years on", the Annual Conference will bring together experts from across the microelectronics sector to discuss the latest technologies and developments, as well as providing a platform to highlight current commercial opportunities.

As part of our sponsorship, Inseto is also confirmed as one of the exhibitors at MicroTech 2018 and we look forward to seeing many of our customers, at what has become an excellent, must-attend event.

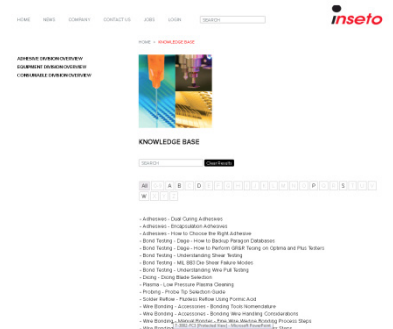
Further details on the Conference can be found on the IMAPS-UK website: www.imaps.org.uk

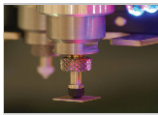
"Knowledge Base" Technical Library

Inseto's "Knowledge Base" is a new, must-see area of our website designed to provide an industry-wide technical library full of information about materials, processes, equipment setup and functions etc., in handy downloadable documents.

This essential resource is free-to-use and available without login via the "Knowledge" menu on the site:
<https://www.inseto.co.uk/knowledge.php>

We will continue to add documents to the directory, however if you have any ideas or suggestions for inclusion, please let us know!

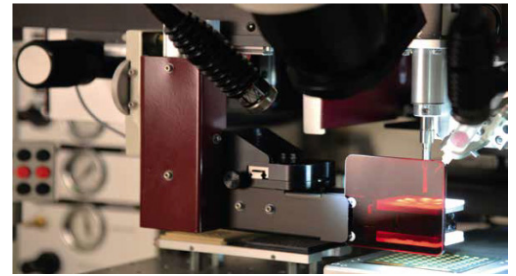




Equipment News

Precision Flip Chip Bonding

Tresky AG, a Swiss manufacturer of high-quality manual die bonding equipment, has recently introduced The Flip Chip Ultra, high-precision bond alignment option at Productronica 2017.



The new module allows users to accurately align devices either prior to pick-up and/or during bonding, where precise bond placement or process control is required. The low-mass unit incorporates an 18 mega pixel ultra HD camera with a 400x digital zoom and split-field optics, as well as integrated LED lights for optimal illumination of various substrates and components. It is quick and simple to use and fits perfectly onto the system's Z axis, which provides a true vertical bond motion, irrespective of the device or bond height.

An extensive range of complementary options is also available to suit almost any die attach process, such as eutectic, thermo-compression, thermo-sonic and epoxy bonding. These include: rapid heating and cooling plates, ultrasonic bond heads, flip chip units, eutectic scrub, heated bond tools, epoxy dispense and stamping, pickup from wafer, wafer, gel or tape etc.

The Flip Chip Ultra unit is available for installation on new T-4909 and T-3000 series bonders and for upgrade on specific models.



Adhesives News

Adhesives for Hot & Sticky Applications

Inseto has added DELOMONOPOX® HT760 to its extensive range of products from DELO Industrial Adhesives, which are ideal for a variety of electronic, automotive, aerospace, oil & gas applications.



DELOMONOPOX® HT760 is a high temperature, heat-cured anhydride adhesive. It boasts a high bond strength after long-term aging (1,000 hours at 250°C) and at temperature (also 250°C), as well as having good temperature stability and thermal and chemical resistance.

The material is not only suitable for extremely high temperatures, but it also withstands aggressive chemicals. It was subjected to compression shear strength tests (FR4 on FR4) after 20 minutes of curing at 150°C, subsequent cooling and exposure to typical automotive fluids. Figure 1 shows the test results – excellent adhesion even after immersion in chemicals such as AdBlue, petrol, diesel, and DI water.

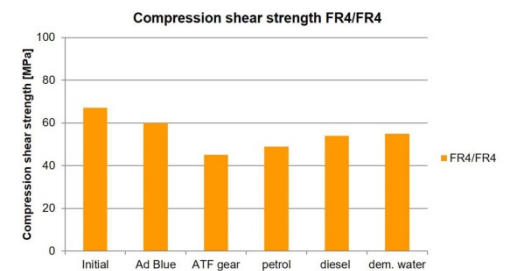


Figure 1

Inseto is DELO Industrial Adhesives' exclusive distributor in the UK and Ireland. Products available through Inseto include an extensive range of UV cured or light activated epoxies, light cured acrylates, light / heat cured epoxies, dual curing materials, light / anaerobic curing adhesives, 2 part polyurethanes, 1 & 2 part epoxies, cyanoacrylates and single part silicones. For further information on these products please visit <https://www.inseto.co.uk/adhesives.php>.

Company News Snippets:

Inseto has successfully completed external audits confirming the company's transition to the latest ISO 9001:2015 standard. The new 2015 standard pays more attention to risk management, interested parties and the context of management within the organization and quality system.

We are pleased to announce that Mr Matt Houston has recently been appointed as Inseto's new Senior Technical Support Engineer responsible for managing the team's activities and schedule.

Inseto is now a member of NMI, the trade association which supports the established Semiconductor Manufacturing and Electronic Systems manufacturing communities by facilitating activities such as knowledge exchange, increased productivity, cost reduction, quality improvement and supplier forums.

See us at the following events in 2018:

- innoLAE 2018, 23-24 January, Cambridge
- IMAPS-UK Annual Conference, 9-10 April, Egham
- FAST Exhibition, 10 May, Motorcycle Museum, Solihull
- IMAPS-Nordic Conference, 12-14 June, Oulu, Finland
- FAST - Fastening & Assembly Solutions, 20 Sept., Duxford
- Engineering Design Show, 17-18 October, Coventry

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